

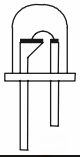


一 華 半 導 體 有 限 公 司
MOSDESIGN SEMICONDUCTOR CORP.

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LED FLASH

M18110



8 LEDS FLASH

8 LEDS 来电显示控制 IC

FEATURES 功能叙述

- Rosc ext. / built-in available.
- Power-on blinking about 5 sec.
- Mode: OSH / LH select default LH.

OSH: one-trigger-on section.

LH: auto change section.

When no signal after 2 sec then LED off.

- Motor : active high to driver motor (64 Hz carry).
- On: connect to VDD LED steady on.

APPLICATION 产品应用

- Key chain, Mobile phone, Toys.

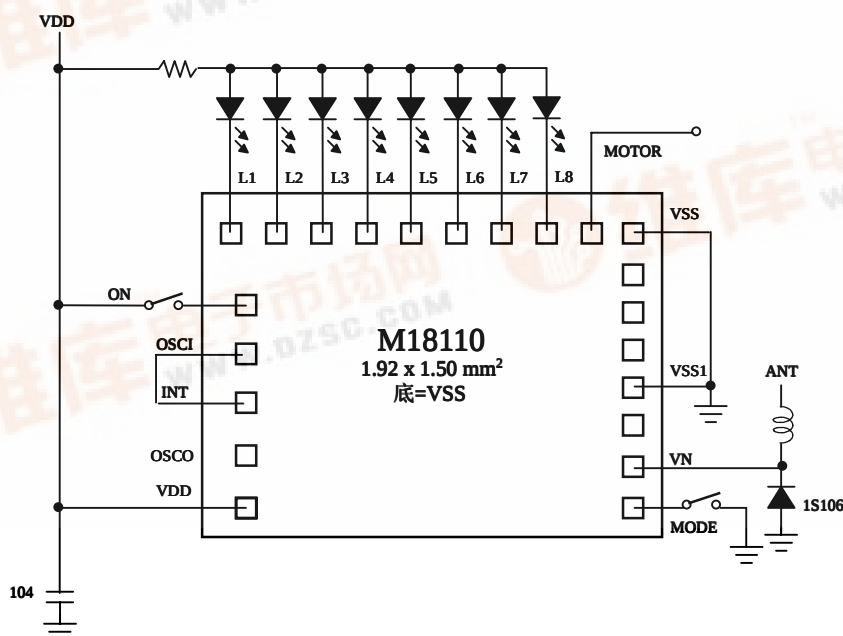
ELECTRICAL CHARACTERISTICS 电气规格

(@V_{DD}=3V unless otherwise specified)

Characteristics	Sym.	Min.	Typ.	Max.	Unit	REMARKS
工作电压 Operating Voltage	V _{DD}	—	3	5	V	
工作电流 Operating Current	I _{OP}	—	0.1	0.5	mA	No load
静态电流 Quiescent Current	I _{SB}	—	1	5	μA	
推动电流 Driving Current	I _{OL}	20	—	—	mA	@ V _{DS} =1.2V
振荡频率 Oscillator Frequency	F _{OSC}	—	256	—	KHz	±30% TOL.
工作温度 Operating Temperature	Temp.	0	25	60	°C	

APPLICATION DIAGRAM 参考电路图

(A) Internal Rosc.



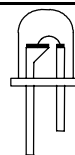


~ 華半導體股份有限公司
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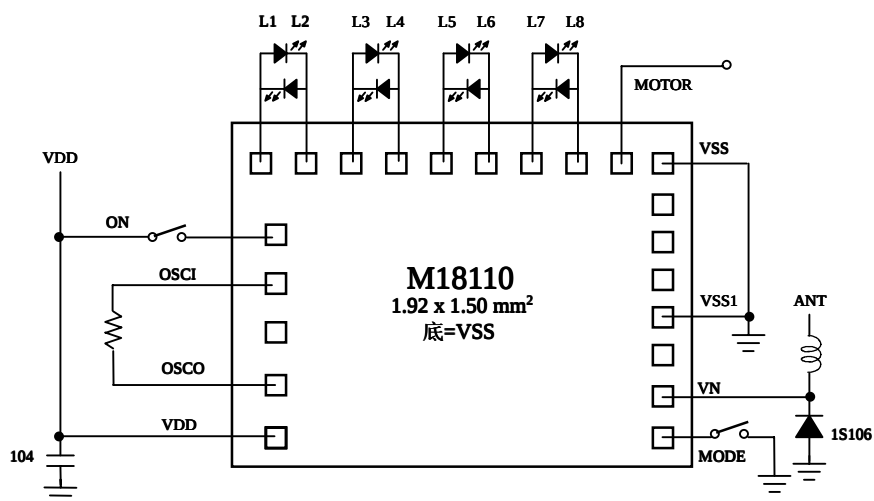
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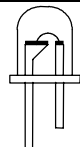
(B) External Rosc.



* VDD、VDD1、VSS & VSS1 must bonding together.

*All specs and applications shown above subject to change without prior notice.

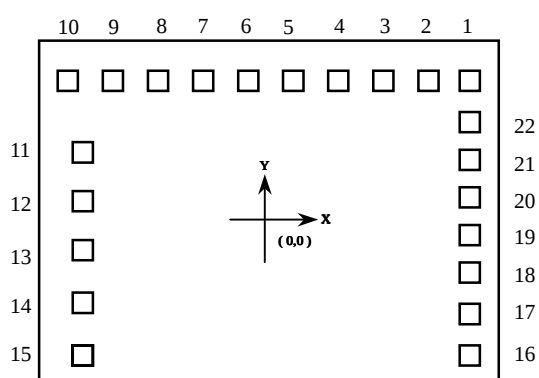
(以上电路及规格仅供参考,本公司得径行修正)

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PAD ASSIGNMENT&POSITION



Unit : um

NO	NAME	X	Y
1	VSS	786.70	526.00
2	MOTOR	627.50	526.00
3	L8	452.60	526.00
4	L7	277.60	526.00
5	L6	102.30	526.00
6	L5	-72.30	526.00
7	L4	-247.40	526.00
8	L3	-422.40	526.00
9	L2	-597.30	526.00
10	L1	-775.20	526.00
11	ON	-716.70	237.40
12	OSCI	-716.70	34.00
13	R	-716.70	-169.40
14	OSCO	-716.70	-372.80
15	VDD	-716.70	-576.10
16	MODE	786.70	-576.20
17	VN	786.70	-418.70
18	VP	786.70	-261.10
19	VSS1	786.70	-106.10
20	TF64	786.70	48.90
21	TSELB	786.70	203.90
22	TESTB	786.70	359.00

* CHIP SIZE ~ 1.92 x 1.50 mm²

* IC substrate should be connected to VSS in PCB (PCB 上 IC 必须接 VSS)

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